Introduction
This application note describes recommended practices and guidelines for the successful assembly of M/A-COM Technology Solutions E-Series surface mount components using automated solder reflow techniques. Incorrect handling, storage, reflow and cleaning may damage the components.

Handling and Storage Precautions
Most E-series components are static sensitive and are packaged accordingly. Appropriate handling precautions should be observed. The typical shelf life of these components is 24 months. However, corrosive, salty or high humidity atmospheres can have an adverse effect on the solderability of contact pads/pins. Manual handling of the components is not recommended.

Component Construction
<table>
<thead>
<tr>
<th>Substrate</th>
<th>Type</th>
<th>Plating Construction</th>
<th>Cover Material (where applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ceramic</td>
<td>Leadless</td>
<td>Electroless Nickel Immersion Gold (ENIG)</td>
<td>High temperature polymer mould High temperature 6/6 nylon disk</td>
</tr>
<tr>
<td>DAP</td>
<td>SOT</td>
<td>Sn over Copper</td>
<td></td>
</tr>
<tr>
<td>FR-4</td>
<td>Leadless</td>
<td>ENIG</td>
<td>High temperature polymer mould High temperature 6/6 nylon disk Galvanised steel</td>
</tr>
</tbody>
</table>

Solder Paste
M/A-COM Technology Solutions E-series components are designed to work with most recommended reflow profiles for the SAC305/SAC405 type solders, and are fully compatible with the standard reflow profiles used for the SN60, SN62 and SN63 solder pastes, including no-clean pastes. For most case styles, a paste thickness of 0.25mm ± 0.05mm will provide an adequate solder joint. For the SM-22 case style, a solder paste thickness of 0.20mm ± 0.025mm is recommended.

Component Placement
E-Series components are designed for placement using automatic Pick and Place equipment. Component placement is critical to negate shorts caused by solder bridging. Most E-series components can accept a side overhang of up to 50% of the pad width, and a toe overhang of up to 10% of pad length. For the SM-22 case style, side overhang must be less than 25%, and toe overhang less than 5%.

General Soldering Precautions: Lead-Free Soldering Process

Relation of qualification profile and actual production profile

The profiles listed in this document are not production reflow profiles, but are related to those profiles with an added margin of safety to account for oven variation, temperature drift, and product variation and process robustness. The actual profile used in production will be dictated primarily by the solder composition selected.

Process Requirements

The ovens used should be 100% convection reflow. Where applicable, thermocouples should be securely attached to the top surface of a representative component to insure the temperature exposure. This can be done three times.

We recommended 90 seconds above 217°C with a maximum temperature of 260°C. The 60 seconds at temperatures >250°C is the maximum duration these package types should be exposed to.

PEB-FREE REFLOW PROFILE ENVELOPE

- EXTREME PROFILE ENVELOPE
- MINIMUM REFLOW ENVELOPE

Condition

Average ramp-up rate (30°C to 217°C)
> 100°C
> 150°C
> 217°C

Peak Temperature

Cool-down rate (Peak to 50°C)
Time from 30°C to 255°C

Exposure

less than 3°C / second
between 360-600 seconds
at least 240 seconds
at least 90 seconds
greater or equal to 255°C at least 15 seconds
less than 6°C / second
no greater than 360 seconds

All temperatures shown are +5/-0°C